



Systematic Studies of sTGC QC Measurements

BRANDON DEATH

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Outline

- New Small Wheel (NSW)
- General Design of small-strip Thin Gap Chambers (sTGC)
- Significance of NSW
- sTGC Assembly Process @ Carleton University
- Analysis Motivation
- Implications for Detector
- Results
- Conclusion

New Small Wheel (NSW)



Figure 1: General Design of New Small Wheel within ATLAS [1][2]

August 22, 2019

Not to scale



Not to scale



Not to scale



Not to scale



sTGC Detection Event

Not to scale



sTGC Detection Event

Not to scale



Significance of NSW

- Currently 90% of Muon triggers are FALSE [3]
 - Will only get worse with increased luminosity
- sTGC provides additional trigger to reduce amount of false detections
- Quicker response time
 - Needed for High-Luminosity upgrade to LHC
- Improves precision tracking
 - Spatial resolution of ~150μm

	L1MU threshold (GeV)	Level-1 rate (kHz)
Currently	$p_{\rm T} > 20$	60 ± 11
	$p_{\rm T} > 40$	29 ± 5
	$p_{\rm T} > 20$ barrel only	7 ± 1
Ungrado	$p_{\rm T} > 20$ with NSW	22 ± 3
opgrade	$p_{\rm T} > 20$ with NSW and EIL4	17 ± 2

Figure 6: Level-1 Single Muon Trigger Rates [3]



Figure 7: Simulated number of events showing various threshold cut-offs

sTGC Assembly @ Carleton University

- Receive Pad/Strip Boards from TRIUMF
- Wind Pad boards with 50 μm gold-plated tungsten wires using winding table (1.8mm pitch)
- Glue boards together into a Singlet (or "Gas Volume")
 - Measure 19-point thickness and 12x10 planarity
- Glue two Singlets into a Doublet (w/ Honeycomb)
 - Measure 19-point thickness and 12x10 planarity
- Glue two Doublets into a Quadruplet (w/ Honeycomb)
 - Measure 19-point thickness and 12x10 planarity
- Glue copper Protection Covers (PC) to either side of Quad
- Attach adapter boards and electronics
- Many QC tests are performed (Pulser, HV, X-Ray)



Figure 8: Assembly of Singlet (Gas Volume) [2]



Figure 9: Thickness (Left) and Planarity (Right) Measurement Locations [4]

Motivation for Analysis

- Measurements are taken at each stage of Quad assembly
- Used to examine construction process
 - Ensure each part falls within allowed tolerances
 - · Gives an overview of how well assembly process has gone so far
- Look for patterns across all Quads
 - Outliers (misentered data or otherwise)
 - Notable discrepancies in measurements
 - Systematic patterns in construction process
- Infer how construction variations will affect the physics involved
- Calibration of detector after installation

Implications for Detector

Thickness Measurements

- Key to the sTGC is tracking resolution (~150μm)
- Inaccurate thickness measurements lead to offset wire position, which affects the tracking of particles

Planarity Measurements

- LASER units are glued onto surface of NSW sTGC wedges
- Calibrate position of wedge with reference point to global coordinate system of ATLAS
- sTGC wedge surfaces must be very flat to give precise calibration



Figure 10: Depiction of offset position tracking with inaccurate calibration

Implications for Detector

X-Ray Test

- Excite gas at different regions and measure the detector's current response
- Very dense electric field lines (2.9kV across 1.4mm)
- *Small* changes in *thickness* produce a *large* change in *gain* (100μm ~ 30%)
- Inaccurate gain will cause incorrect Muon energy calibration

My Work



Figure 11: Raw Data of the thickness measured at 19 points around perimeter of Quadruplet QS3.P.1

19-Point Thickness Analysis – QS3





19-Point Thickness Analysis – QS3





Planarity Analysis – QS3





Mean planarity of each point falls within tolerance:

Average ± 150µm



Planarity Analysis – QS3



Figure 15: 3D Plot of mean planarity values shown in Figure 13.



-1.075

-1.100 E

-1.150 👌

-1.175 Puer

-1.225

Mean planarity of each point falls within tolerance:

Average ± 150µm

Example X-Ray Test Analysis – QS3







Figure 17: Histogram of heatmap bin Current compared with average Gap 2 Pivot Singlets

Conclusion

- I have developed a Python script to be used as an analysis tool during assembly of sTGC detectors as well as for calibration during & after installation
- It will be available for all international collaborators to use during their sTGC production as well

Further Additions to Analysis Tool

- X-Ray Test
 - Correlate to thickness/planarity measurements
 - · Compare with cosmic ray test results
- High Voltage Tests
 - Checks for breakdown of gap (sparking, current leak, inconsistencies)
- Pulser Test
 - Tests connectivity of wires, strips and boards
 - Used to troubleshoot during assembly process
 - Records waveform shape and Vpp for each channel

Questions?

References

- Brookhaven and the Large Hadron Collider, Brookhaven National Laboratory, Stony Brook University [Accessed June 21, 2019] https://www.bnl.gov/ATLAS/
- 2) Chav Chhiv Chau, Upgrade of the ATLAS Muon Spectrometer Thin Gap Chambers and their electronics for the HL-LHC phase, ATLAS Muon Collaboration, Carleton University, February 21,2019 http://cds.cern.ch/record/2666950/files/ATL-MUON-SLIDE-2019-076.pdf
- 3) ATLAS New Small Wheel Technical Design Report, ATLAS Collaboration, CERN-LHCC-2013-006, ATLAS-TDR-20-2013, p.173, July 2013
- 4) sTGC Assembly Manual, ATLAS Muon Collaboration, April 5,2018

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Additional Slides

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NSW Trigger



Figure 18: Diagram showing how the NSW can be an additional trigger to help reduce false detections

sTGC Assembly Stages



Figure 19: Assembly stages of a NSW wedge [4]

sTGC Assembly Parts

- Cover Wire Rules
- Doublets
- Gas Volumes
- Half-Pads
- Half-Strips
- Honeycomb Frames
- Pad Plates

- Protection Cover Plates
- Protection Covers
- Quadruplets
- Strip Plates
- Wire Rulers
- Wire Supports

			Active Area								Frames (peripheral) area							
						Scheme						Scheme						
	Layer	Elem.	Ma	aterial	0	1	2		Elem.		viaterial	0	1	2				
			Code	Name	PS200	P5150	P150S200			Code	Name	P\$200	P\$150	P1505200				
	Cover	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				
ove	0	10	2	FR4	0.183	0.183	0.183		10	2	FR4	0.183	0.183	0.183				
õ	Giue	10	8	Ероху	0.030	0.030	0.030		10	8	Ероху	0.030	0.030	0.030				
Ň	Honoyoomb	16	2	Epoxy	4.050	4 970	4.970		15	7	Eiber gloss	E 000	4 020	4 0 2 0				
u de	noneycomb	10	2	Faper	4.950	4.070	4.070		15	1	Fiber glass	5.000	4.920	4.920				
Ť	Glue	10	8	Epoxy	0.025	0.025	0.025		10	8	Epory	0.030	0.030	0.030				
	Olde	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.030				
		3	2	FR4	0.200	0.150	0.150		3	2	FR4	0.200	0.150	0.150				
	D 10 1	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				
	Pad Board	2	2	FR4	1.065	1.165	1.165		2	2	FR4	1.065	1.165	1.165				
		8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				
e 4		4	2	FR4	0.183	0.183	0.183		4	2	FR4	0.183	0.183	0.183				
	Glue		4) 		10	8	Epoxy	0.030	0.030	0.030				
Ę		9	5	Graphite	0.010	0.010	0.010			1000		al and the state of the state		20.020000				
Gas volt	100000000000000000000000000000000000000	13	1	CO2-np	1.420	1.420	1.420		1	2	FR4	1.400	1.400	1.400				
	Gas Volume	14	6	Tungsten	0.050	0.050	0.050		12	8	Epoxy	0.050	0.050	0.050				
		13	1	CO2-np	1.420	1.420	1.420		1	2	FR4	1.400	1.400	1.400				
		9	5	Graphite	0.010	0.010	0.010											
	Glue					0.150			10	8	Epoxy	0.030	0.030	0.030				
		6	2	FR4	0.200	0.150	0.200		6	2	FR4	0.200	0.150	0.200				
	Strip Board	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				
		0	2	Coppor	0.019	0.019	0.019		0	4	Coppor	0.019	0.019	0.019				
	Gluo	10	8	Enory	0.010	0.010	0.010		10	-4	Epoxy	0.010	0.010	0.010				
Ē	Olde	11	8	Epoxy	0.030	0.025	0.000		10	U	сролу	0.050	0.050	0.000				
)0	Honevcomb	16	3	Paper	4 950	4 870	4 870		15	7	Fiber glass	5 000	4 920	4 920				
he	, is is joint	11	8	Fnoxy	0.025	0.025	0.025			12.6	Tiber glass	5.000	4.520	4.020				
우	Glue	10	8	Epoxy	0.030	0.030	0.030		10	8	Fpoxy	0.030	0.030	0.030				
	oido	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				
		5	2	FR4	1.265	1.365	1.365		5	2	FR4	1.265	1.365	1.365				
	Strip Board	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				
		6	2	FR4	0.200	0.150	0.200		6	2	FR4	0.200	0.150	0.200				
	Glue		2		\$5				10	8	Epoxy	0.030	0.030	0.030				
		9	5	Graphite	0.010	0.010	0.010											
Ime 3		13	1	CO2-np	1.420	1.420	1.420		1	2	FR4	1.400	1.400	1.400				
	Gas Volume	14	6	Tungsten	0.050	0.050	0.050		12	8	Epoxy	0.050	0.050	0.050				
olt		13	1	CO2-np	1.420	1.420	1.420		1	2	FR4	1.400	1.400	1.400				
s 2		9	5	Graphite	0.010	0.010	0.010											
Ga	Glue	50 00	3						10	8	Epoxy	0.030	0.030	0.030				
		4	2	FR4	0.183	0.183	0.183		4	2	FR4	0.183	0.183	0.183				
		8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				
	Pad Board	2	2	FR4	1.065	1.165	1.165		2	2	FR4	1.065	1.165	1.165				
	r au Duaiu	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				
		3	2	FR4	0.200	0.150	0.150		3	2	FR4	0.200	0.150	0.150				
		8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018				



Total

27

	Layer		Elem.	M	aterial	0	Schen 1	ne 2	E	Elem.	N	/laterial	0	Schem 1	1e 2		Schem 0	e
		0.732		Code	Name	PS200	PS150	P150S200			Code	Name	PS200	P\$150	P150S200	-	PS200	
	- 1	Ol-	10	1 0	Francis	1 0 020	0.000	0.000	-	40	0	F	0.000	0.000	0.020	0.02	-	-
tront	ti -	Giue	10	8	Epoxy	0.030	0.030	0.030		10	8	Ероху	0.030	0.030	0.030	0.03	8	
	2	Honeycomb	16	3	Paper	1 950	4 870	4 870		15	7	Fiber alass	5 000	1 920	1 920	5.00	5.06	
	lei	rioneyconib	11	8	Enoxy	0.025	0.025	0.025		13		r iber giass	5.000	4.520	4.520	5.00	0.00	
	운 :	Glue	10	8	Epoxy	0.030	0.030	0.030		10	8	Epoxy	0.030	0.030	0.030	0.03		
-	-		8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018	8		
		Pad Board	3	2	FR4	0.200	0.150	0.150		3	2	FR4	0.200	0.150	0.150			
			8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018	1.50		
			2	2	FR4	1.065	1.165	1.165		2	2	FR4	1.065	1.165	1.165			
			8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018			
	8	Glue	4	2	FR4	0.105	0.105	0.105		4	8	Enon/	0.103	0.030	0.103	0.03		
	me	Giuc	9	5	Graphite	0.010	0.010	0.010	r - 7	10		сролу	0.000	0.000	0.000	0.00		
	In		13	1	CO2-np	1.420	1.420	1 4 2 0		1	2	FR4	1 400	1,400	1 400		5.91	
	Ň	Gas Volume	14	6	Tungsten	0.050	0.050	0.050		12	8	Epoxy	0.050	0.050	0.050	2.85	100000	
	ğ		13	1	CO2-np	1.420	1.420	1.420		1	2	FR4	1.400	1.400	1.400			
	Ĩ.		9	5	Graphite	0.010	0.010	0.010					181165-55	39.09-52	2003623265			
		Glue					CONTRACTOR -	1		10	8	Epoxy	0.030	0.030	0.030	0.03		
		Strip Board	6	2	FR4	0.200	0.150	0.200		6 8	2	FR4	0.200	0.150	0.200			
Doublet 1			8	4	Copper	0.018	0.018	0.018			4	Copper	0.018	0.018	0.018	1.50		
			5	2	FR4 Connor	1.265	1.365	1.365		5	2	FR4 Connor	1.265	1.365	1.365	1000000000		
		Glue	10	8	Enory	0.010	0.010	0.010		10	8	Epopy	0.010	0.010	0.010	0.03		-
	E	Honeycomb	11	8	Epoxy	0.025	0.025	0.025		10	0	сроху	0.050	0.030	0.050	0.05		
	yce		16	3	Paper	4.950	4.870	4.870		15	7	Fiber glass	5.000	4,920	4,920	5.00	5.06	16
	one		11	8	Ероху	0.025	0.025	0.025					10000000		2040.00	- Andrewski (
	Ĭ	Glue	10	8	Epoxy	0.030	0.030	0.030		10	8	Epoxy	0.030	0.030	0.030	0.03		
		Strip Board	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018			
			5	2	FR4	1.265	1.365	1.365		5	2	FR4	1.265	1.365	1.365	1.50		
			6	4	ED/	0.010	0.010	0.010		6	4	Copper ED/	0.010	0.010	0.010			
	1	Glue	0	6	1114	0.200	0.150	0.200		10	8	Epoxy	0.030	0.030	0.030	0.03		
			9	5	Graphite	0.010	0.010	0.010										
	ume 1		13	1	CO2-np	1.420	1.420	1.420		1	2	FR4	1.400	1.400	1.400	press and		
		Gas Volume	14	6	Tungsten	0.050	0.050	0.050		12	8	Epoxy	0.050	0.050	0.050	2.85	-	
	No l		13	1	CO2-np	1.420	1.420	1.420		1	2	FR4	1.400	1.400	1.400		5.91	
	as	Chuo	9	9 5 Graphite 0.010 0.010 0.010 10 10 0.000 0.000		0.020	0.020	0.02	-									
	0	Gide	1	2	FR4	0 183	0 183	0 183	r H	4	2	EPOXy FR4	0.030	0.030	0.030	0.03	-	
			8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018			
		Ded Pound	2	2	FR4	1.065	1.165	1.165		2	2	FR4	1.065	1.165	1.165	1.50		
		Pad Board	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018	1.50		
			3	2	FR4	0.200	0.150	0.150		3	2	FR4	0.200	0.150	0.150			
			8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018			
	-	Glue	10	8	Epoxy	0.030	0.030	0.030		10	8	Epoxy	0.030	0.030	0.030	0.03		
	0	Honeycomb	16	8	Epoxy	1 950	0.025	4 870		15	7	Eibor glass	5.000	1 920	1 920	5.00		
	+	Honeycomb	10	8	Enoxy	0.025	0.025	0.025		15		Tiber glass	5.000	4.320	4.320	5.00	5.26	
	ey	Glue	10	8	Epoxy	0.030	0.030	0.030		10	8	Epoxy	0.030	0.030	0.030	0.03	0.20	
	Lo Lo	Course	7	2	FR4	0.183	0.183	0.183		7	2	FR4	0.183	0.183	0.183	0.20		
	+	Cover	8	4	Copper	0.018	0.018	0.018		8	4	Copper	0.018	0.018	0.018	0.20		
	97. 19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00 (19.00			100	1000			-		9	e.	2000			73			-
To	otal					49.34	49.34	49.54	0				49.34	49.34	49.54	49.34	49.34	49